

EV Group and Teramount Collaborate to Implement Packaging Technologies for Photonic Integrated Circuits – March 7, 2022

semiconductor packaging news

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March 7, 2022

[Semiconductor Sales Increase 27% Year-to-Year in January](#)

The Semiconductor Industry Association (SIA) announced global semiconductor industry sales were \$50.7 billion in the month of January 2022, an increase of 26.8% over over the January 2021 total of \$40.0 billion and 0.2% less than the December 2021 total of \$50.9 billion. Monthly sales are compiled by the World Semiconductor Trade Statistics (WSTS) organization and represent ...



[Semiconductor Industry Association](#)

[New JCET Bumping Line in South Korea](#)

Automotive, wireless, computing and other devices have been qualified on this new 12 Inch Wafer Bumping Line which is an integral part of JCETs advanced flip chip packaging offerings. JCET



[Large Capacity Plasma Treatment System - FlexTRAK-SHS](#)

9.6-liter plasma process chamber handles larger, or more, strips increasing throughput and productivity for electronics/semiconductor packaging. MARCH | Nordson Electronics Solutions



[Gina Raimondo: "Let's get back to the business of building microchips in America"](#)

The global semiconductor shortage, a major driver of ballooning U.S. inflation, is as much a national security issue as an economic issue, U.S. Secretary of Commerce ...

[MIT News](#)

[How accurately can you measure bumps?](#)

Accurately measure BGA bumps, vias, pin position & height, diameter as well as x/y dimensions. Learn about systems that provide highly accurate and repeatable measurement ...

[Technical Paper](#)

[TSMC joins Intel-led chiplet alliance as founding member](#)

Taiwan Semiconductor Manufacturing Co. (TSMC), the world's largest contract chipmaker, has become one of the key players joining hands to co-establish an industry ...

[Focus Taiwan](#)

[Technical Papers](#)

- [Achieving Success in Automotive Leadframe Packages](#)
- [New Packaging FA Solutions Using Correlated X-ray Microscopy and LaserFIB](#)
- [How accurately can you measure bumps?](#)
- [Advanced Packaging and Electronic Assembly Cleaning Fluid Innovation](#)

[The XRF engineered for semiconductors](#)

Polycapillary optics focus to 7.5µm FWHM. X-Y stage with >300mm travel and +/- 1µm stage precision. Z-protection prevents sample collision. Auto wafer handling workstations. Read more.



[Bowman XRF](#)

Today's Sponsor

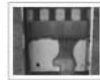


[Test Your Knowledge](#)

In 1982 Time Magazine named a thing as its "Man of the Year". What thing was it? See answer below.

[Transform Your Sample Prep with LaserFIB](#)

Rapidly access deeply buried features with precise targeting. Get site-specific cross-section results in minutes to hours. How? Watch our webinar. ZEISS Microscopy



[Press Releases](#)

[EV Group and Teramount Collaborate to Implement Packaging Technologies for Photonic Integrated Circuits](#)

EV Group (EVG) and Teramount announce a collaboration on implementing wafer-level optics to solve a major obstacle of silicon photonics, namely fiber chip packaging. The collaboration ...

[EV Group](#)

[Sondrel explains the 10 steps to model and design a complex SoC](#)

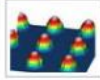
The shrinking of nodes means that chips are becoming ever more complex and require ever larger teams of engineers. To ensure that the design time of a chip does not increase ...

[Sondrel](#)

- [Improving Si and SiC Wafer Dicing Yields with Thermal Laser Separation](#)
- [Critical Considerations for Electronic Component Tin Whisker Mitigation](#)
- [Why AgCoat® Prime, why now?](#)

How to accurately measure bumps

Accurately measure BGA bumps, vias, pin position & height, diameter & x/y dimensions. Learn how to provide accurate & repeatable measurement results at inspection speeds.



cyberTECHNOLOGIES

Optimizing cycle times with Openair-Plasma

Plasma surface treatment has uses in semiconductor manufacturing, such as wire bonding, die bonding, thermal compress bonding, and pre-molding.



Plasmatreat GmbH

[Folding phones could soon be mainstream, with Apple thought to have one in the works](#)

The vast majority of new smartphones on display at this year's Mobile World Congress — an event that tech giants use to showcase their latest handsets — looked remarkably ...

CNBC

[Samsung suspends chip and cellphone shipments to Russia](#)

Samsung Electronics Co has suspended product shipments to Russia due to current geopolitical developments, joining a growing list of companies from Apple Inc to ...

Taipei Times

[China May Win in AI Computing](#)

The technology driver for the next decade is AI. Quoting Applied Materials CEO Gary Dickerson, "Are we ready for the biggest opportunity of our lifetime?" Dickerson ...

EE Times

NanoResolution MRS™ Sensor
for Packaging Inspection and Metrology

Micro Bump

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[Week In Review: Manufacturing, Test](#)

ASE, AMD, Arm, Google, Intel, Meta, Microsoft, Qualcomm, Samsung, and TSMC have announced the formation of a consortium that will establish a die-to-die ...

Semiconductor Engineering

[Graphcore Supercharges IPU with Wafer-on-Wafer](#)

Graphcore unveiled its third-generation intelligence processing unit (IPU), the first processor to be built using 3D wafer-on-wafer (WoW) technology. Codenamed the Bow ...

EE Times

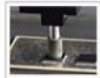
[Micron sampling 176-layer NAND SSD for data centers](#)

Micron Technology has announced it is sampling what the company claims is the world's first vertically-integrated 176-layer NAND solid-state drive (SSD) for data center ...

Digitimes

Sintering Bonding Process

During the sintering process, the chip is bonded very well to the substrate by means of silver paste. The silver particles are connected to one another by diffusion processes.



Tresky Automation

Bonder for high-density interconnects

The universal SUSS XBS300 Hybrid Bonding Platform allows for fully automated W2W (wafer-to-wafer) and collective D2W (die-to-wafer) hybrid bonding. Learn more.



SUSS MicroTec

[Indium Corporation Introduces Liquid Flip-Chip Flux](#)

Indium Corporation has expanded its flux portfolio with a new liquid flux designed to meet process needs for low-temperature flip-chip applications. WS-3910 is a water-soluble, halogen-free ...

Indium Corporation

[2022 IEEE 72nd ECTC Conference](#)

The ECTC conference is the premier international event that brings together the best in packaging, components & microelectronic systems science, technology & education. May 31 - July 3.



ECTC

Quote of the Day

"Do first things first, and second things not at all."

Peter Drucker

[Thermally Conductive Adhesive System](#)

Master Bond EP40TC is a two part, thermally conductive, electrically insulative epoxy that combines convenient processing with superior strength properties.



Master Bond

[The New Technology Solutions for Advanced SiP Devices](#)

This white paper will discuss technologies that are currently being applied to System in Package (SiP) and forecast what to expect in the future.



Amkor Technology, Inc.

What Year Was It?

[Bell Patents the Telephone](#)

29-year-old Alexander Graham Bell receives a patent for his revolutionary new invention - the telephone.



[The day was Mar 7. What year was it?](#)

[Do thin wafers have you frazzled?](#)

Our new ADJUST-A-VAC allows you to reduce the vacuum pressure from just below atmospheric pressure to up to ten inches of mercury. A LED bar display shows the vacuum level.



Virtual Industries, Inc.

[A Die Attach with High-Thermal Conductivity](#)

A high thermal conductivity (20W/m²K) die attach for power devices and LEDs. Excellent adhesion to gold, silver, Alloy 42, ENIG, and beryllium copper.

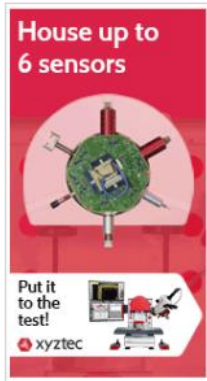


NAGASE

[Intel, other industry leaders set up UCIe consortium](#)

Intel has announced it is among industry titans working to advance the future of semiconductor architectural innovations with new UCIe standard. Intel, along with ASE ...

Digitimes



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Submicron die bonder for

- silicon photonics
- wafer-level packaging

MRSI MYCRONIC



Custom Engineering

- Removes Organic Residues
- Activates surfaces for adhesion
- Prepares surfaces for Direct Bonding

ONTOS Atmospheric Plasma

Cartoon of the Day



"Our books are balanced. 50% of our numbers are real and 50% are made up."

Copyright © Randy Glasbergen

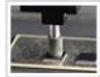
Calendar

- [Mar 7, 2022: IMAPS Device Packaging Conference](#)
- [Mar 7, 2022: Semiconductor Reliability and Product Qualification](#)
- [Mar 24, 2022: Overview of Semiconductor Manufacturing/Chandler, AZ](#)
- [Apr 3, 2022: SEMI Industry Strategy Symposium \(ISS\)](#)

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Tresky Automation



Bonder for high-density interconnects

The universal SUSS XBS300 Hybrid Bonding Platform allows for fully automated W2W (wafer-to-wafer) and collective D2W (die-to-wafer) hybrid bonding. Learn more. **SUSS MicroTec**



Metal support wafer for wafer bonding

Its thermal expansion is close to semiconductor wafer to improve the reliability of LEDs. Materials can be chosen from Cu-W, Cu-Mo or Mo. Read more to find the other features.

A.L.M.T. Corp.



Test Your Knowledge Answer

In 1982 Time Magazine named a thing as its "Man of the Year". What thing was it?

Answer: Personal computer on December 26, 1982

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